

### FEATURES

- High Speed (Equal Access and Cycle Times)
  - 12/15/20/25/35 ns (Commercial)
  - 15/20/25/35/45 ns (Industrial)
  - 20/25/35/45/55/70 ns (Military)
- Low Power
- Single 5V±10% Power Supply
- Easy Memory Expansion Using  $\overline{CE}$  and  $\overline{OE}$  Inputs
- Common Data I/O
- Three-State Outputs
- Fully TTL Compatible Inputs and Outputs
- Advanced CMOS Technology
- Fast  $t_{OE}$
- Automatic Power Down
- Packages
  - 28-Pin 300 mil DIP, SOJ, TSOP
  - 28-Pin 300 mil Ceramic DIP
  - 28-Pin 600 mil Plastic and Ceramic DIP
  - 28-Pin CERPACK
  - 28-Pin Solder Seal Flat Pack
  - 28-Pin SOP
  - 28-Pin LCC (350 mil x 550 mil)
  - 32-Pin LCC (450 mil x 550 mil)

### DESCRIPTION

The P4C1256 is a 262,144-bit high-speed CMOS static RAM organized as 32K x 8. The CMOS memory requires no clocks or refreshing, and has equal access and cycle times. Inputs are fully TTL-compatible. The RAM operates from a single 5V±10% tolerance power supply.

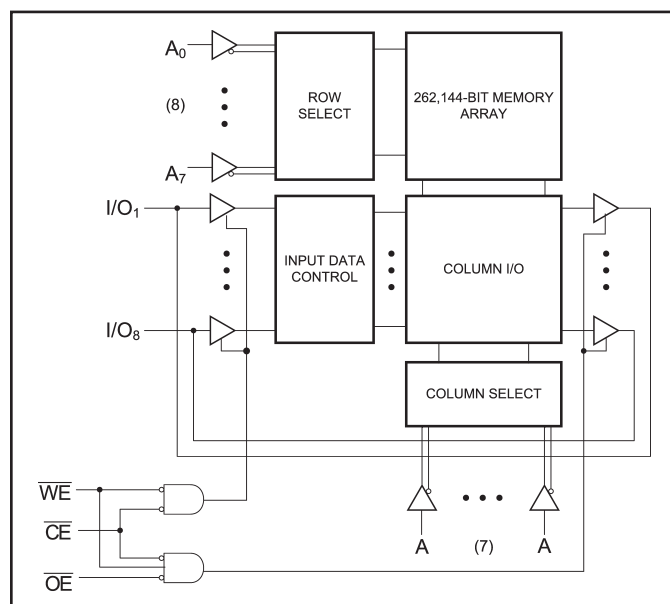
Access times as fast as 12 nanoseconds permit greatly enhanced system operating speeds. CMOS is utilized to reduce power consumption to a low level. The P4C1256 is a member of a family of PACE RAM™ products offering fast access times.

The P4C1256 devices provides asynchronous operation

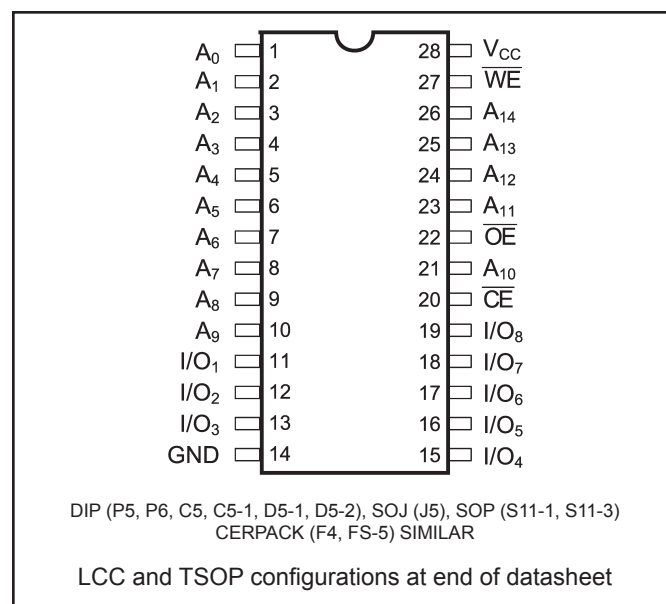
with matching access and cycle times. Memory locations are specified on address pins  $A_0$  to  $A_{14}$ . Reading is accomplished by device selection ( $\overline{CE}$ ) and output enabling ( $\overline{OE}$ ) while write enable ( $\overline{WE}$ ) remains HIGH. By presenting the address under these conditions, the data in the addressed memory location is presented on the data input/output pins. The input/output pins stay in the HIGH Z state when either  $\overline{CE}$  or  $\overline{OE}$  is HIGH or  $\overline{WE}$  is LOW.

Package options for the P4C1256 include 28-pin DIP, SOJ, and TSOP packages. For military temperature range, Ceramic DIP and LCC packages are available.

### FUNCTIONAL BLOCK DIAGRAM



### PIN CONFIGURATIONS





## MAXIMUM RATINGS<sup>(1)</sup>

Sym	Parameter	Value	Unit
V <sub>CC</sub>	Power Supply Pin with Respect to GND	-0.5 to +7	V
V <sub>TERM</sub>	Terminal Voltage with Respect to GND (up to 7.0V)	-0.5 to V <sub>CC</sub> + 0.5	V
T <sub>A</sub>	Operating Temperature	-55 to +125	°C
T <sub>BIAS</sub>	Temperature Under Bias	-55 to +125	°C
T <sub>STG</sub>	Storage Temperature	-65 to +150	°C
P <sub>T</sub>	Power Dissipation	1.0	W
I <sub>OUT</sub>	DC Output Current	50	mA

## RECOMMENDED OPERATING CONDITIONS

Grade <sup>(2)</sup>	Ambient Temp	GND	V <sub>CC</sub>
Commercial	0°C to 70°C	0V	5.0V ± 10%
Industrial	-40°C to +85°C	0V	5.0V ± 10%
Military	-55°C to +125°C	0V	5.0V ± 10%

## CAPACITANCES<sup>(4)</sup>

(V<sub>CC</sub> = 5.0V, T<sub>A</sub> = 25°C, f = 1.0MHz)

Sym	Parameter	Conditions	Typ	Unit
C <sub>IN</sub>	Input Capacitance	V <sub>IN</sub> =0V	8	pF
C <sub>OUT</sub>	Output Capacitance	V <sub>OUT</sub> =0V	10	pF

## DC ELECTRICAL CHARACTERISTICS

(Over Recommended Operating Temperature & Supply Voltage)<sup>(2)</sup>

Sym	Parameter	Test Conditions	P4C1256		P4C1256L		Unit	
			Min	Max	Min	Max		
V <sub>IH</sub>	Input High Voltage		2.2	V <sub>CC</sub> + 0.5	2.2	V <sub>CC</sub> + 0.5	V	
V <sub>IL</sub>	Input Low Voltage		-0.5 <sup>(3)</sup>	0.8	-0.5 <sup>(3)</sup>	0.8	V	
V <sub>HC</sub>	CMOS Input High Voltage		V <sub>CC</sub> - 0.2	V <sub>CC</sub> + 0.5	V <sub>CC</sub> - 0.2	V <sub>CC</sub> + 0.5	V	
V <sub>LC</sub>	CMOS Input Low Voltage		-0.5 <sup>(3)</sup>	0.2	-0.5 <sup>(3)</sup>	0.2	V	
V <sub>OL</sub>	Output Low Voltage (TTL Load)	I <sub>OL</sub> = +8 mA, V <sub>CC</sub> = Min		0.4		0.4	V	
V <sub>OH</sub>	Output High Voltage (TTL Load)	I <sub>OH</sub> = - 4 mA, V <sub>CC</sub> = Min	2.4		2.4		V	
I <sub>LI</sub>	Input Leakage Current	V <sub>CC</sub> = Max, V <sub>IN</sub> = GND to V <sub>CC</sub>	MIL	-10	+10	-5	+5	μA
			IND/COM	-5	+5	N/A	N/A	
I <sub>LO</sub>	Output Leakage Current	V <sub>CC</sub> = Max, $\overline{CE} = V_{IH}$ , V <sub>OUT</sub> = GND to V <sub>CC</sub>	MIL	-10	+10	-5	+5	μA
			IND/COM	-5	+5	N/A	N/A	
I <sub>SB</sub>	Standby Power Supply Current (TTL Input Levels)	$\overline{CE} \geq V_{IH}$ , V <sub>CC</sub> = Max, f = Max, Outputs Open	MIL	—	45	—	30	mA
			IND/COM	—	30	—	N/A	
I <sub>SB1</sub>	Standby Power Supply Current (CMOS Input Levels)	$\overline{CE} \geq V_{HC}$ , V <sub>CC</sub> = Max, f = 0, Outputs Open V <sub>IN</sub> ≤ V <sub>LC</sub> or V <sub>IN</sub> ≥ V <sub>HC</sub>	MIL	—	20	—	10	mA
			IND/COM	—	10	—	N/A	

N/A = Not applicable

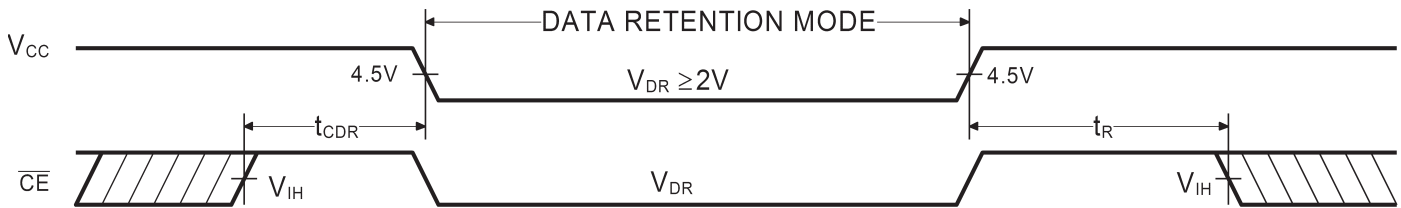
## DATA RETENTION CHARACTERISTICS (P4C1256L Military Temperature Only)

Sym	Parameter	Test Conditions	Min	Typ* V <sub>CC</sub> =		Max V <sub>CC</sub> =		Unit
				2.0V	3.0V	2.0V	3.0V	
V <sub>DR</sub>	V <sub>CC</sub> for Data Retention		2.0					V
I <sub>CCDR</sub>	Data Retention Current	$\overline{CE} \geq V_{CC} - 0.2V$ , $V_{IN} \geq V_{CC} - 0.2V$ or $V_{IN} \leq 0.2V$		10	15	100	200	μA
t <sub>CDR</sub>	Chip Deselect to Data Retention Time		0					ns
t <sub>R</sub> †	Operation Recovery Time		t <sub>RC</sub> §					ns

\* T<sub>A</sub> = +25°C§ t<sub>RC</sub> = Read Cycle Time

† This Parameter is guaranteed but not tested

## DATA RETENTION WAVEFORM



## POWER DISSIPATION CHARACTERISTICS VS. SPEED

Sym	Parameter	Temperature Range	-12	-15	-20	-25	-35	-45	-55	-70	Unit
I <sub>CC</sub>	Dynamic Operating Current*	Commercial	170	160	155	150	145	N/A	N/A	N/A	mA
		Industrial	N/A	170	165	160	155	150	N/A	N/A	mA
		Military	N/A	N/A	170	165	160	155	150	150	mA

\* V<sub>CC</sub> = 5.5V. Tested with outputs open. f = Max. Switching inputs are 0V and 3V.  $\overline{CE} = V_{IL}$ ,  $\overline{OE} = V_{IH}$ .

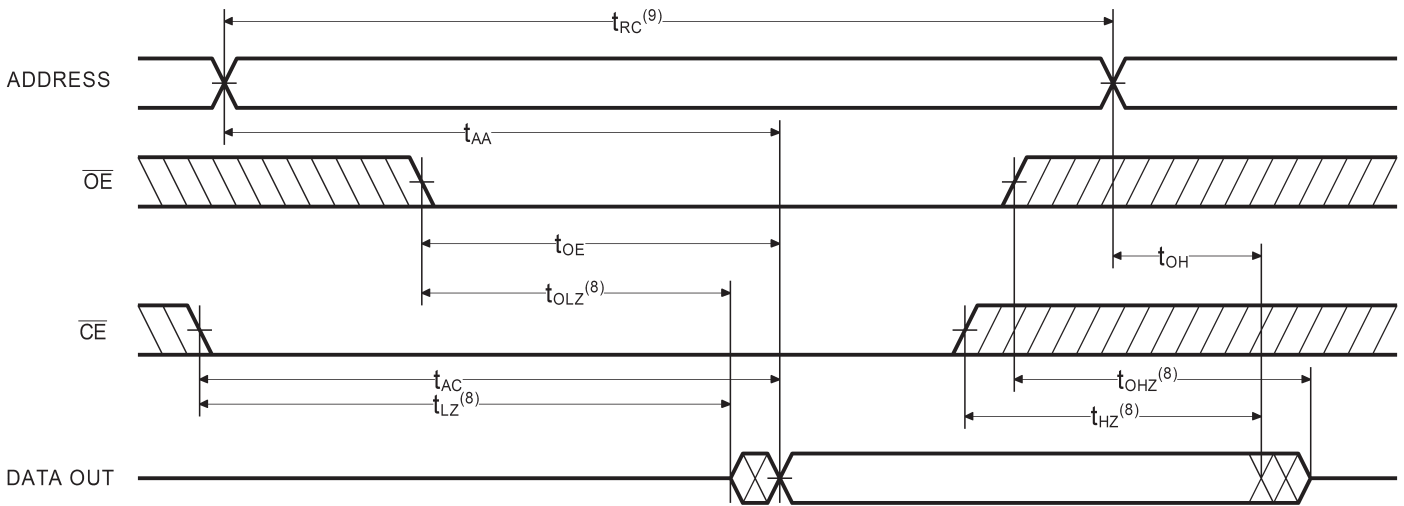
## AC ELECTRICAL CHARACTERISTICS—READ CYCLE

(V<sub>CC</sub> = 5V ± 10%, All Temperature Ranges)<sup>(2)</sup>

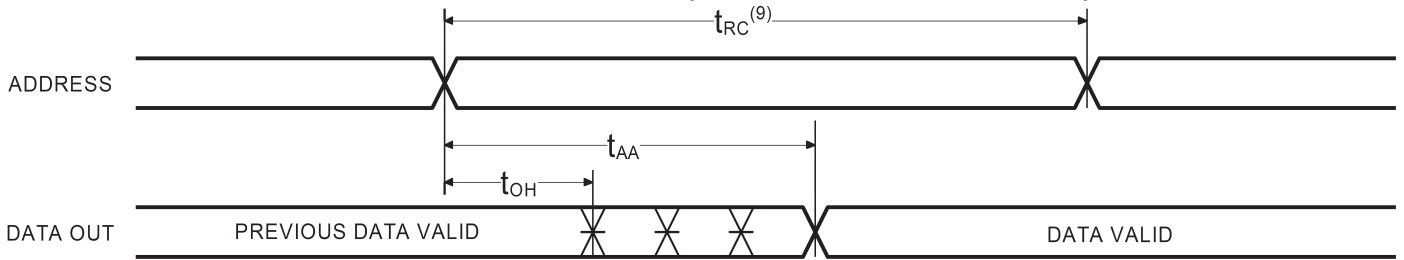
Sym	Parameter	-12		-15		-20		-25		-35		-45		-55		-70		Unit
		Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	
t <sub>RC</sub>	Read Cycle Time	12		15		20		25		35		45		55		70		ns
t <sub>AA</sub>	Address Access Time		12		15		20		25		35		45		55		70	ns
t <sub>AC</sub>	Chip Enable Access Time		12		15		20		25		35		45		55		70	ns
t <sub>OH</sub>	Output Hold from Address Change	2		2		2		3		3		3		3		3		ns
t <sub>LZ</sub>	Chip Enable to Output in Low Z	2		2		2		3		3		3		3		3		ns
t <sub>HZ</sub>	Chip Disable to Output in High Z		5		8		9		11		15		20		25		30	ns
t <sub>OE</sub>	Output Enable Low to Data Valid		5		7		9		10		15		20		25		30	ns
t <sub>OLZ</sub>	Output Enable Low to Low Z	0		0		0		0		0		0		0		0		ns
t <sub>OHZ</sub>	Output Enable High to High Z		5		7		9		11		15		20		25		30	ns
t <sub>PU</sub>	Chip Enable to Power Up Time	0		0		0		0		0		0		0		0		ns
t <sub>PD</sub>	Chip Disable to Power Down Time		12		15		20		20		20		25		30		35	ns



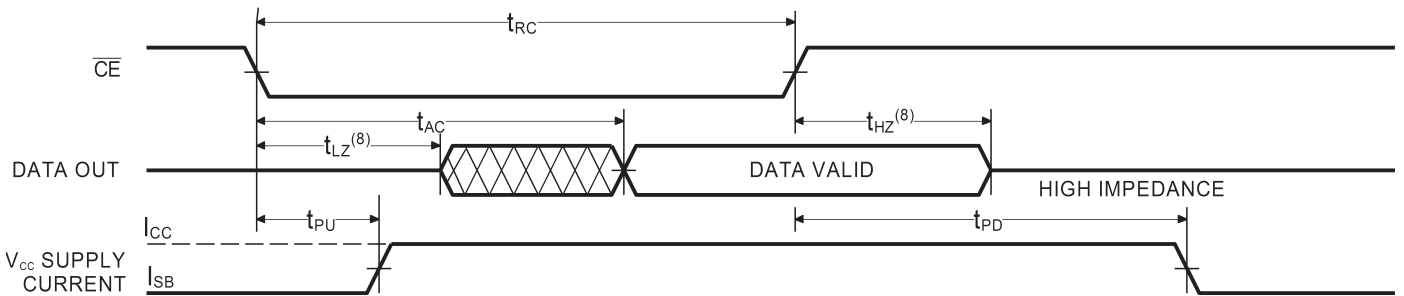
**TIMING WAVEFORM OF READ CYCLE NO. 1 ( $\overline{OE}$  CONTROLLED)<sup>(5)</sup>**



**TIMING WAVEFORM OF READ CYCLE NO. 2 (ADDRESS CONTROLLED)<sup>(5,6)</sup>**



**TIMING WAVEFORM OF READ CYCLE NO. 3 ( $\overline{CE}$  CONTROLLED)**



**Notes:**

1. Stresses greater than those listed under MAXIMUM RATINGS may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to MAXIMUM rating conditions for extended periods may affect reliability.
2. Extended temperature operation guaranteed with 400 linear feet per minute of air flow.
3. Transient inputs with  $V_{IL}$  and  $I_{IL}$  not more negative than  $-3.0V$  and  $-100mA$ , respectively, are permissible for pulse widths up to 20ns.
4. This parameter is sampled and not 100% tested.
5.  $\overline{WE}$  is HIGH for READ cycle.
6.  $\overline{CE}$  is LOW and  $\overline{OE}$  is LOW for READ cycle.
7. ADDRESS must be valid prior to, or coincident with  $\overline{CE}$  transition LOW.
8. Transition is measured  $\pm 200$  mV from steady state voltage prior to change, with loading as specified in Figure 1. This parameter is sampled and not 100% tested.
9. Read Cycle Time is measured from the last valid address to the first transitioning address.

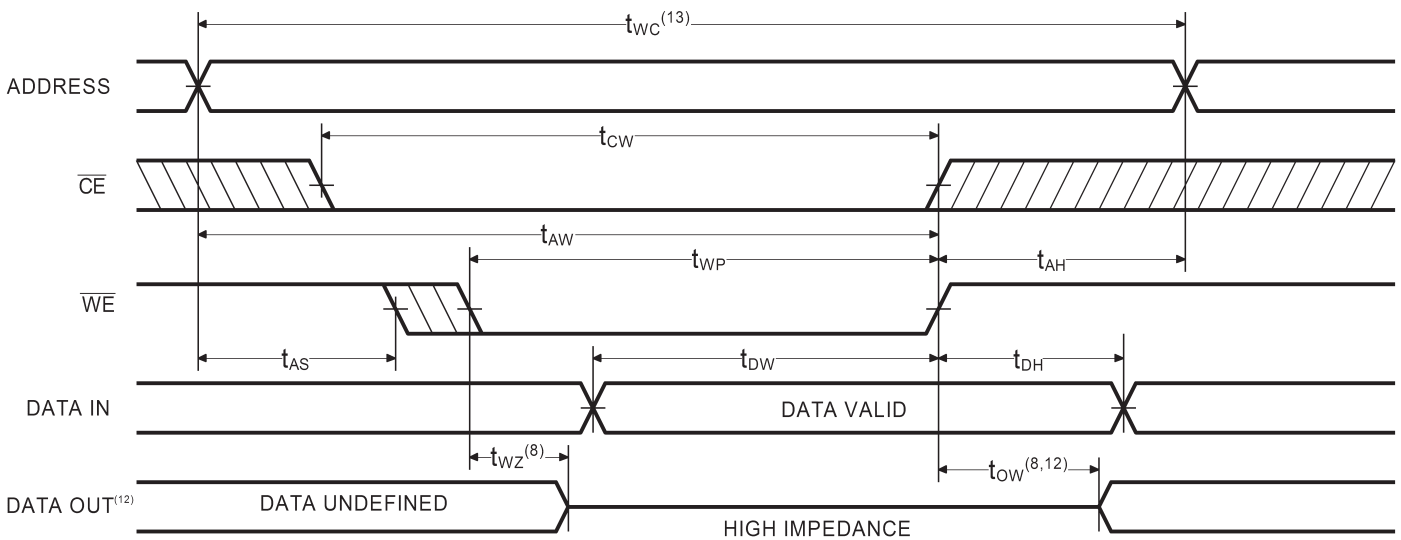


## AC CHARACTERISTICS—WRITE CYCLE

( $V_{CC} = 5V \pm 10\%$ , All Temperature Ranges)<sup>(2)</sup>

Sym	Parameter	-12		-15		-20		-25		-35		-45		-55		-70		Unit
		Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	
$t_{WC}$	Write Cycle Time	12		15		20		25		35		45		55		70		ns
$t_{CW}$	Chip Enable Time to End of Write	9		10		15		18		22		30		35		40		ns
$t_{AW}$	Address Valid to End of Write	9		10		15		20		25		35		40		45		ns
$t_{AS}$	Address Setup Time	0		0		0		0		0		0		0		0		ns
$t_{WP}$	Write Pulse Width	9		11		15		18		22		25		30		35		ns
$t_{AH}$	Address Hold Time	0		0		0		0		0		0		0		0		ns
$t_{DW}$	Data Valid to End of Write	8		9		11		13		15		20		25		30		ns
$t_{DH}$	Data Hold Time	0		0		0		0		0		0		0		0		ns
$t_{WZ}$	Write Enable to Output in High Z		7		8		10		11		15		18		25		30	ns
$t_{OW}$	Output Active from End of Write	3		3		3		3		3		3		3		3		ns

### TIMING WAVEFORM OF WRITE CYCLE NO. 1 ( $\overline{WE}$ CONTROLLED)<sup>(10,11)</sup>



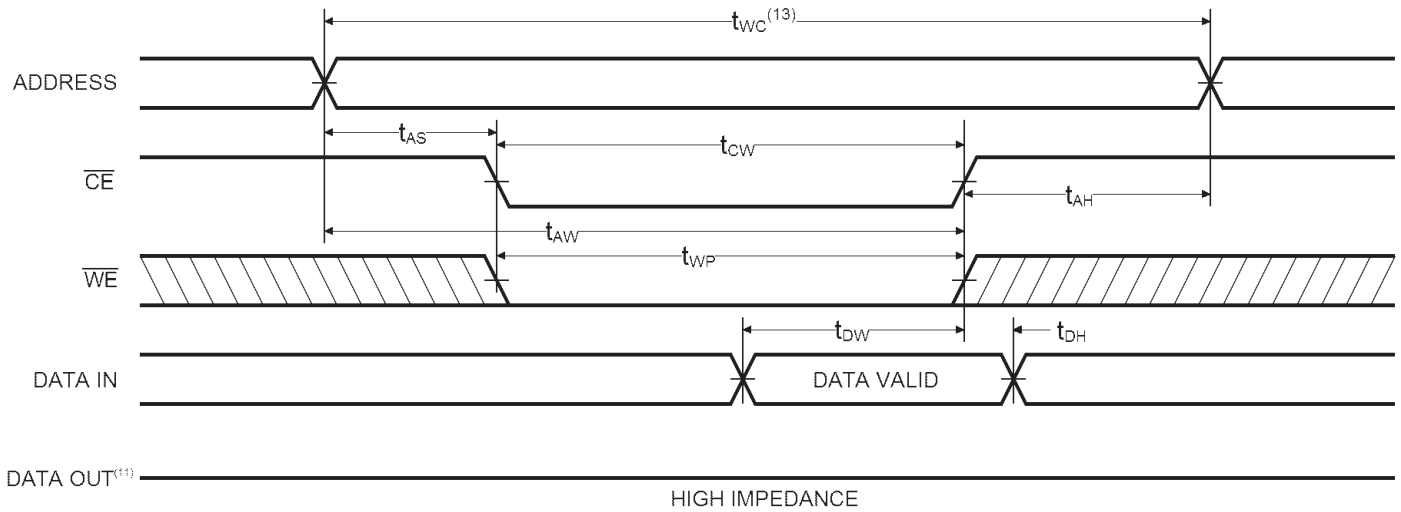
Notes:

- 10.  $\overline{CE}$  and  $\overline{WE}$  must be LOW for WRITE cycle.
- 11.  $\overline{OE}$  is LOW for this WRITE cycle to show  $t_{WZ}$  and  $t_{OW}$ .
- 12. If  $\overline{CE}$  goes HIGH simultaneously with  $\overline{WE}$  HIGH, the output remains in a high impedance state

- 13. Write Cycle Time is measured from the last valid address to the first transitioning address.



### TIMING WAVEFORM OF WRITE CYCLE NO. 2 ( $\overline{CE}$ CONTROLLED)<sup>(10)</sup>



### AC TEST CONDITIONS

Input Pulse Levels	GND to 3.0V
Input Rise and Fall Times	3ns
Input Timing Reference Level	1.5V
Output Timing Reference Level	1.5V
Output Load	See Figures 1 and 2

### TRUTH TABLE

Mode	$\overline{CE}$	$\overline{OE}$	$\overline{WE}$	I/O	Power
Standby	H	X	X	High Z	Standby
$D_{OUT}$ Disabled	L	H	H	High Z	Active
Read	L	L	H	$D_{OUT}$	Active
Write	L	X	L	High Z	Active

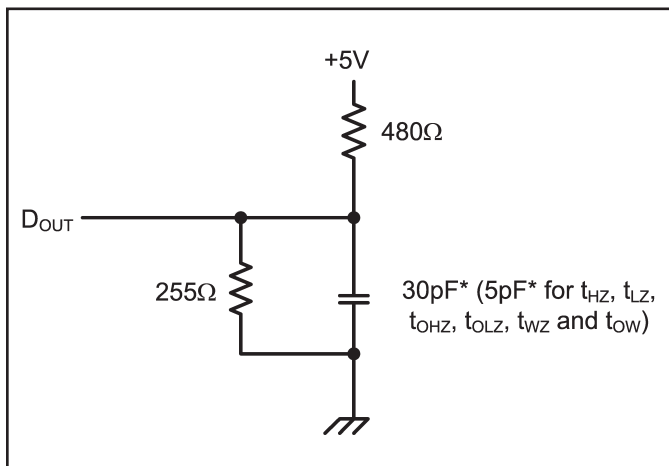


Figure 1. Output Load

\* including scope and test fixture.

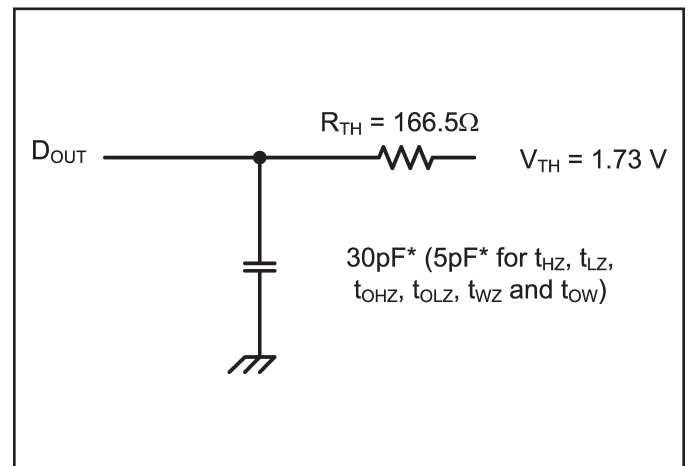


Figure 2. Thevenin Equivalent

**Note:**

Because of the ultra-high speed of the P4C1256, care must be taken when testing this device; an inadequate setup can cause a normal functioning part to be rejected as faulty. Long high-inductance leads that cause supply bounce must be avoided by bringing the  $V_{CC}$  and ground planes directly up to the contactor fingers. A 0.01  $\mu$ F high frequency capacitor

is also required between  $V_{CC}$  and ground. To avoid signal reflections, proper termination must be used; for example, a 50 $\Omega$  test environment should be terminated into a 50 $\Omega$  load with 1.73V (Thevenin Voltage) at the comparator input, and a 116 $\Omega$  resistor must be used in series with  $D_{OUT}$  to match 166 $\Omega$  (Thevenin Resistance).

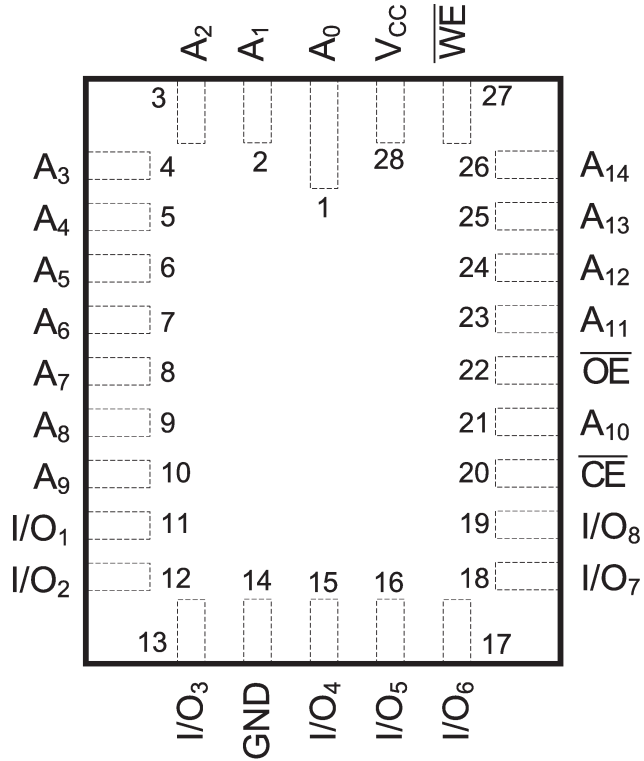


# ORDERING INFORMATION

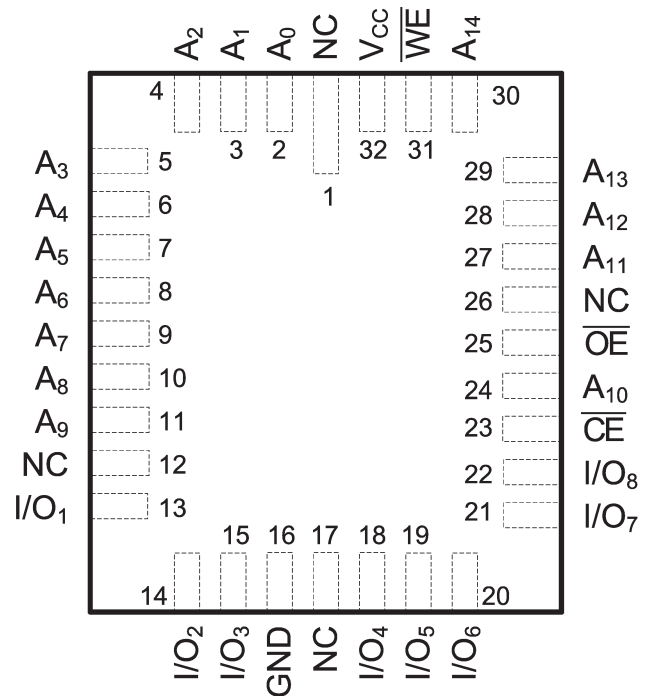
P4C1256	L	xx	x	x	LF
Device Type	Low Power	Speed	Package	Processing	Lead Free
					Lead Free Designation (LF=RoHS compliant; Blank=Standard)
				C	0°C to +70°C
				I	-40°C to +85°C
				M	-55°C TO +125°C
				MB	Mil. Temp with MIL-STD-883 Class B Compliance
			C	Ceramic Side Brazed DIP, 300 mil	
			CW	Ceramic Side Brazed DIP, 600 mil	
			D	Ceramic DIP (CERDIP), 300 mil	
			DW	Ceramic DIP (CERDIP), 600 mil	
			F	CERPACK	
			FS	Solder Seal Flat Pack	
			J	Plastic SOJ, 300 Mil	
			L28	Rectangular 28-pin LCC (350 x 550 mil)	
			L32	Rectangular 32-pin LCC (450 x 550 mil)	
			P	Plastic DIP, 300 mil	
			P6	Plastic DIP, 600 mil	
			T	Plastic TSOP	
			S	Plastic SOP (S11-1 Package)	
			SS	Plastic SOP (S11-3 Package)	
		12, 15, 20, 25, 35, 45, 55, 70 ns			
					Low Power Designation (L=Low Power; Blank=None)
					32K x 8 SRAM



### LCC PIN CONFIGURATIONS



28-Pin LCC (L5)



32-Pin LCC (L6)



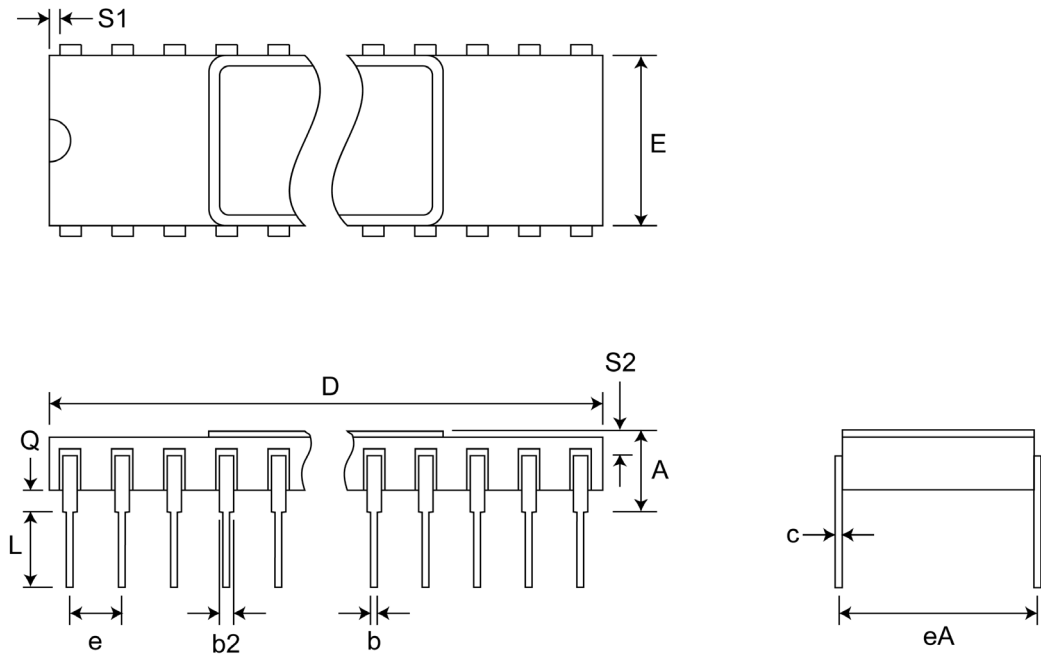
TSOP (T1)





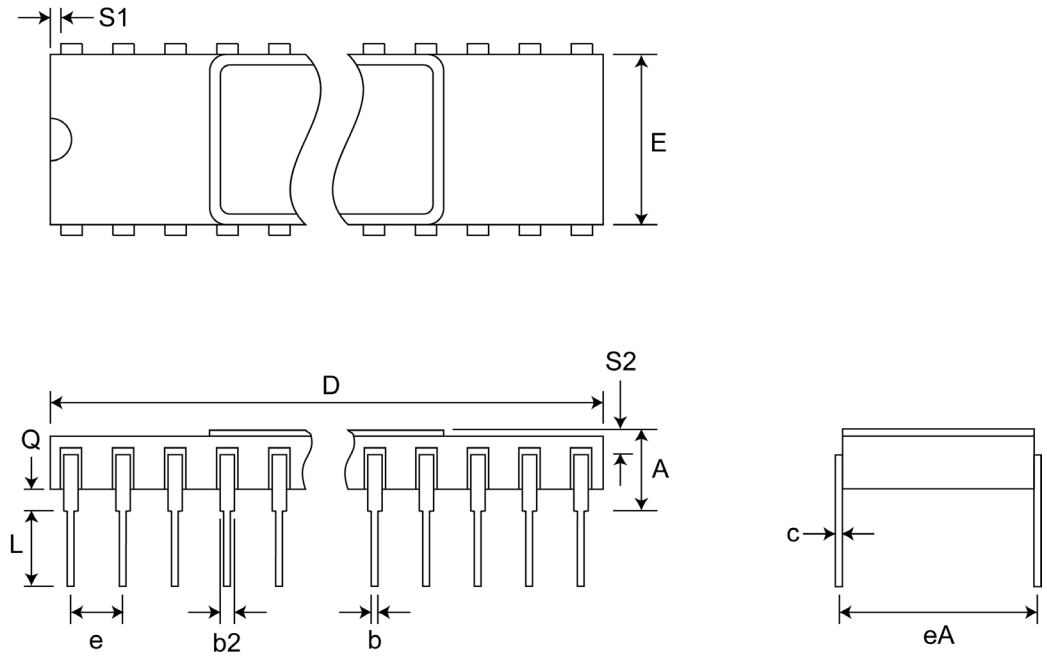
Pkg #	C5	
# Pins	28 (300 mil)	
Symbol	Min	Max
A	-	0.225
b	0.014	0.026
b2	0.045	0.065
C	0.008	0.018
D	-	1.485
E	0.240	0.310
eA	0.300 BSC	
e	0.100 BSC	
L	0.125	0.200
Q	0.015	0.070
S1	0.005	-
S2	0.005	-

**SIDE BRAZED CERAMIC DUAL IN-LINE PACKAGE (300 MILS)**



Pkg #	C5-1	
# Pins	28 (600 mil)	
Symbol	Min	Max
A	-	0.232
b	0.014	0.026
b2	0.045	0.065
C	0.008	0.018
D	-	1.490
E	0.500	0.610
eA	0.600 BSC	
e	0.100 BSC	
L	0.125	0.200
Q	0.015	0.060
S1	0.005	-
S2	0.005	-

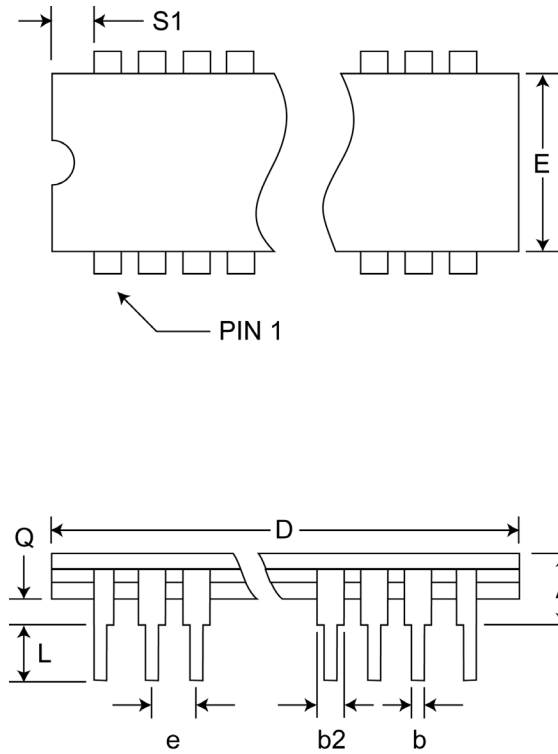
**SIDE BRAZED CERAMIC DUAL IN-LINE PACKAGE (600 MILS)**





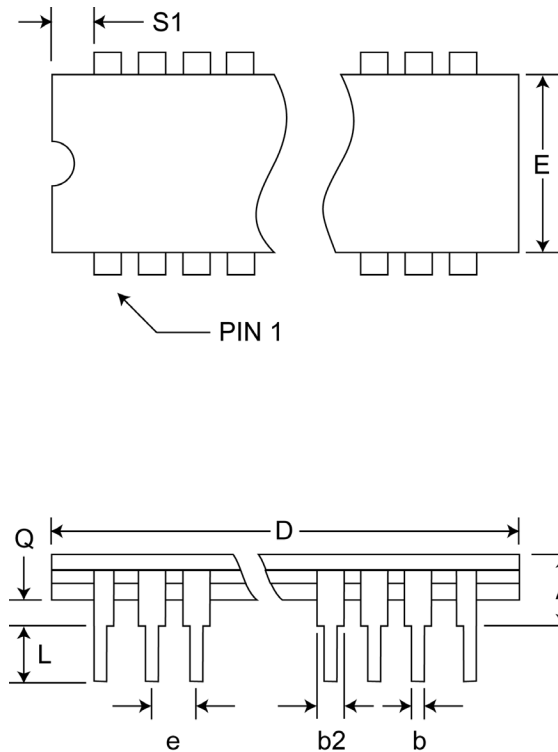
Pkg #	D5-1	
# Pins	28 (600 mil)	
Symbol	Min	Max
A	-	0.232
b	0.014	0.026
b2	0.045	0.065
C	0.008	0.018
D	-	1.490
E	0.500	0.610
eA	0.600 BSC	
e	0.100 BSC	
L	0.125	0.200
Q	0.015	0.060
S1	0.005	-
$\alpha$	0°	15°

**CERDIP DUAL IN-LINE PACKAGE**



Pkg #	D5-2	
# Pins	28 (300 mil)	
Symbol	Min	Max
A	-	0.225
b	0.014	0.026
b2	0.045	0.065
C	0.008	0.018
D	-	1.485
E	0.240	0.310
eA	0.300 BSC	
e	0.100 BSC	
L	0.125	0.200
Q	0.015	0.060
S1	0.005	-
$\alpha$	0°	15°

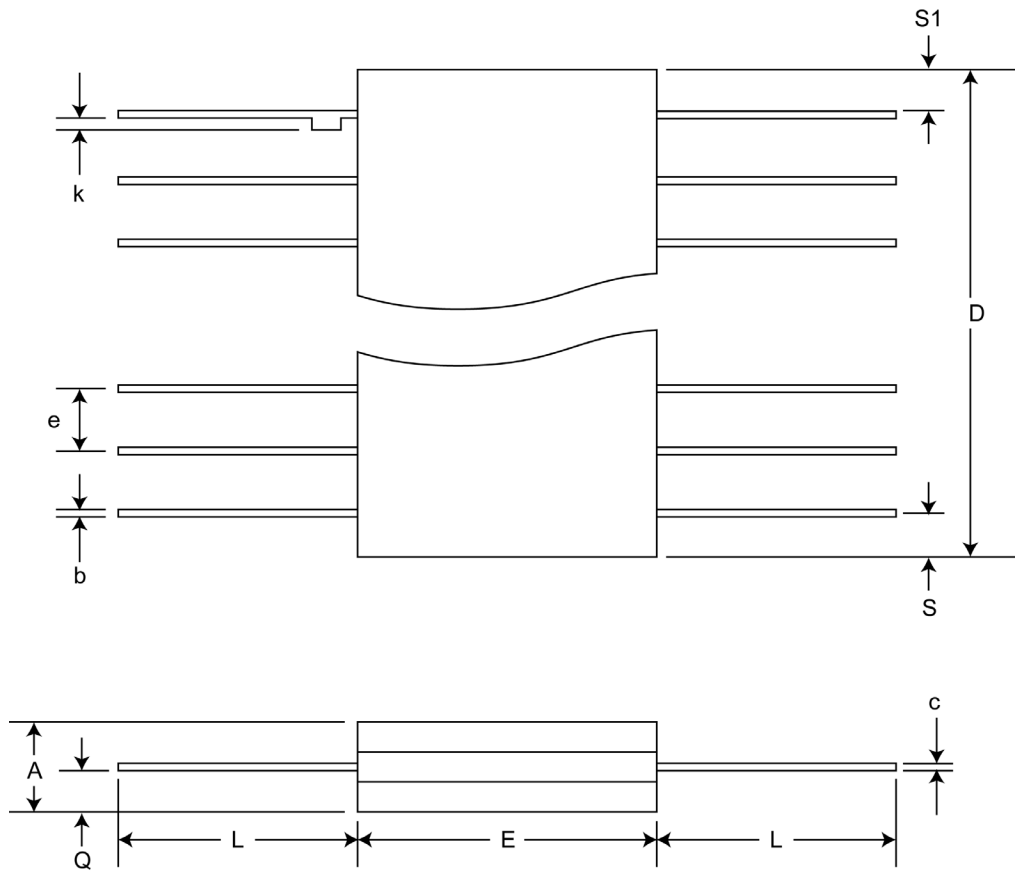
**CERDIP DUAL IN-LINE PACKAGE**





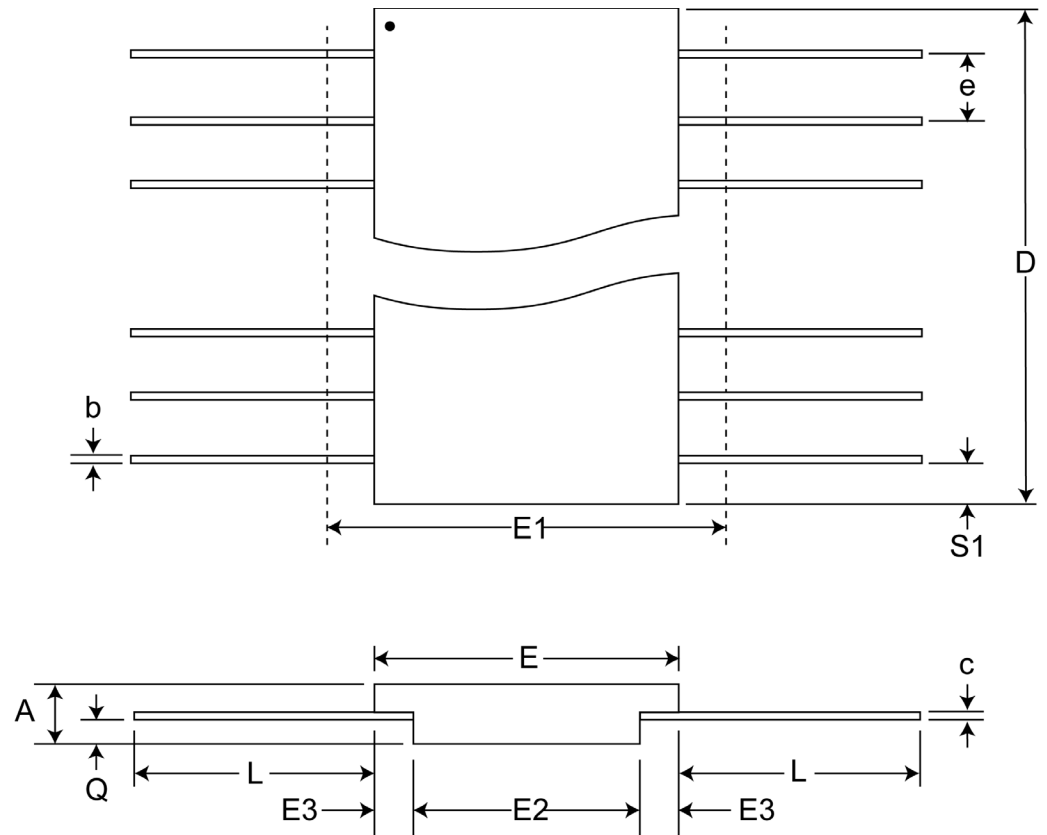
Pkg #	<b>F4</b>	
# Pins	28	
Symbol	Min	Max
A	0.060	0.090
b	0.015	0.022
c	0.004	0.009
D	-	0.730
E	0.330	0.380
e	0.050 BSC	
k	0.005	0.018
L	0.250	0.370
Q	0.026	0.045
S	-	0.085
S1	0.005	-

**CERPACK CERAMIC FLAT PACKAGE**



Pkg #	<b>FS-5</b>	
# Pins	28	
Symbol	Min	Max
A	0.090	0.130
b	0.015	0.022
c	0.004	0.009
D	-	0.740
E	0.380	0.420
E1	-	0.440
E2	0.180	-
E3	0.030	-
e	0.050 BSC	
L	0.250	0.370
Q	0.026	0.045
S1	0.000	-

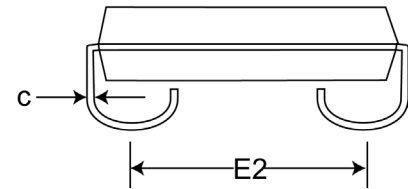
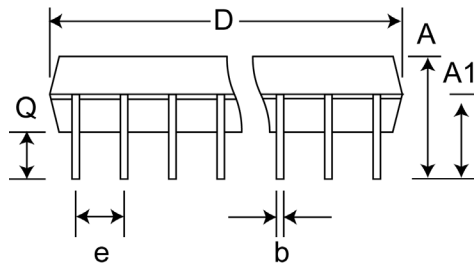
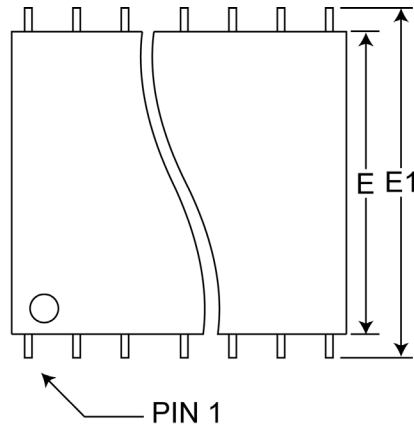
**SOLDER SEAL FLAT PACK**





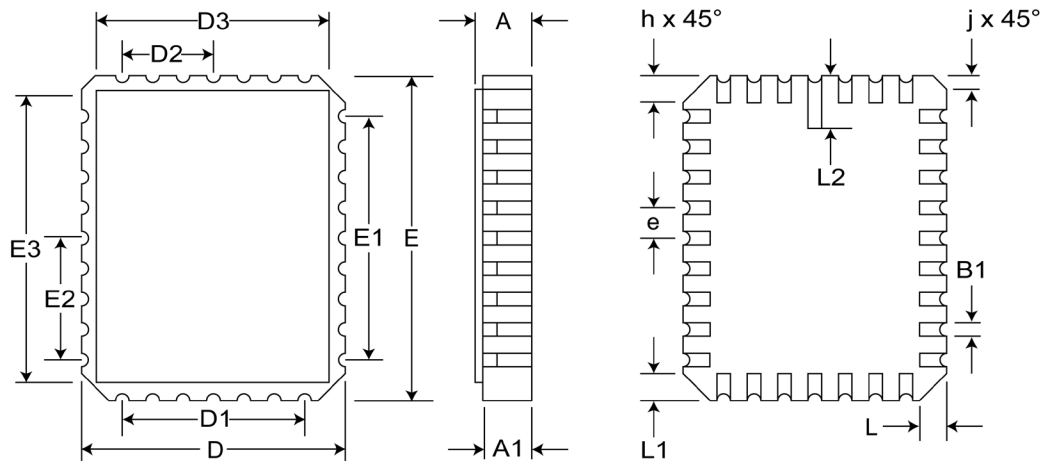
**SOJ SMALL OUTLINE IC PACKAGE**

Pkg #	<b>J5</b>	
# Pins	28 (300 mil)	
Symbol	<b>Min</b>	<b>Max</b>
A	0.120	0.148
A1	0.078	-
b	0.014	0.020
C	0.007	0.011
D	0.700	0.730
e	0.050 BSC	
E	0.292	0.300
E1	0.335	0.347
E2	0.262	0.272
Q	0.025	-



Pkg #	<b>L5</b>	
# Pins	28	
Symbol	<b>Min</b>	<b>Max</b>
A	0.060	0.075
A1	0.050	0.065
B1	0.022	0.028
D	0.342	0.358
D1	0.200 BSC	
D2	0.100 BSC	
D3	-	0.358
E	0.540	0.560
E1	0.400 BSC	
E2	0.200 BSC	
E3	-	0.558
e	0.050 BSC	
h	0.040 REF	
j	0.020 REF	
L	0.045	0.055
L1	0.045	0.055
L2	0.075	0.095
ND	5	
NE	9	

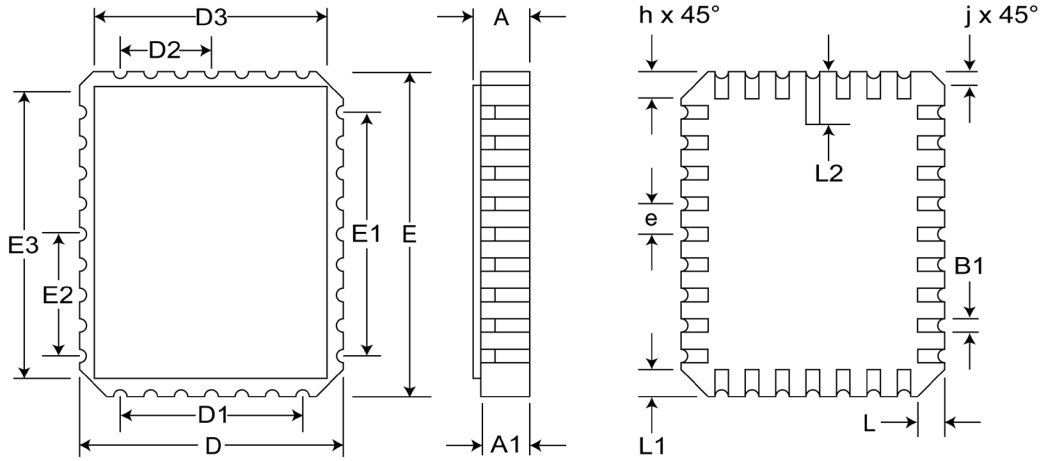
**RECTANGULAR LEADLESS CHIP CARRIER (28 PINS)**





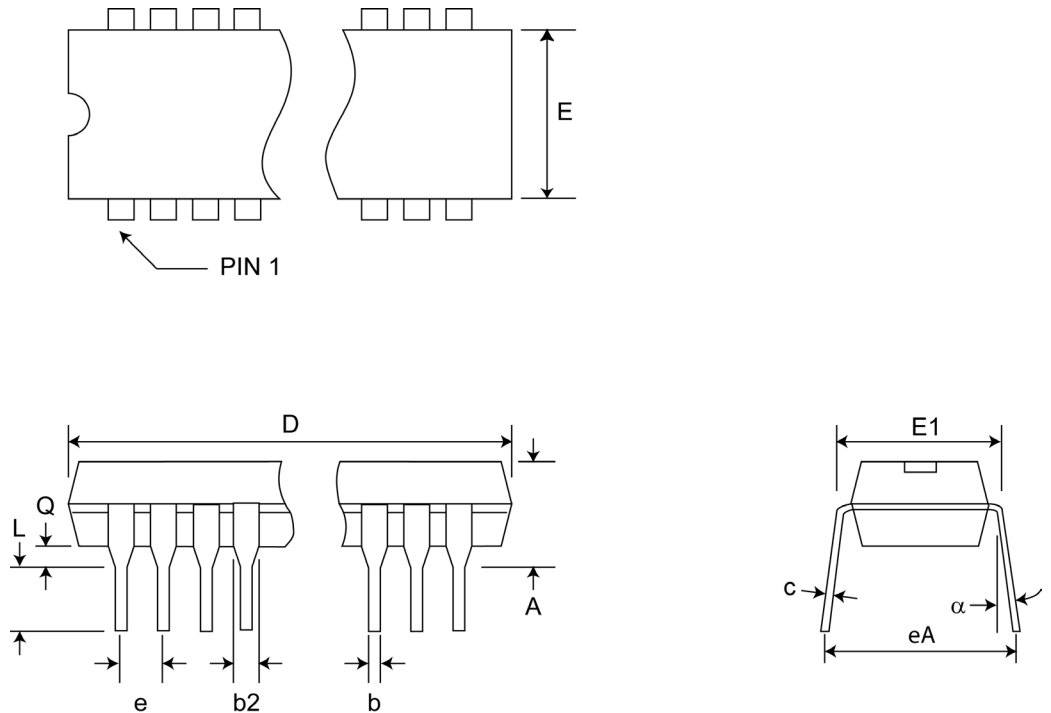
### RECTANGULAR LEADLESS CHIP CARRIER (32 PINS)

Pkg #	<b>L6</b>	
# Pins	32	
Symbol	<b>Min</b>	<b>Max</b>
A	0.060	0.075
A1	0.050	0.065
B1	0.022	0.028
D	0.442	0.458
D1	0.300 BSC	
D2	0.150 BSC	
D3	-	0.458
E	0.540	0.560
E1	0.400 BSC	
E2	0.200 BSC	
E3	-	0.558
e	0.050 BSC	
h	0.040 REF	
j	0.020 REF	
L	0.045	0.055
L1	0.045	0.055
L2	0.075	0.095
ND	7	
NE	9	



### PLASTIC DUAL IN-LINE PACKAGE

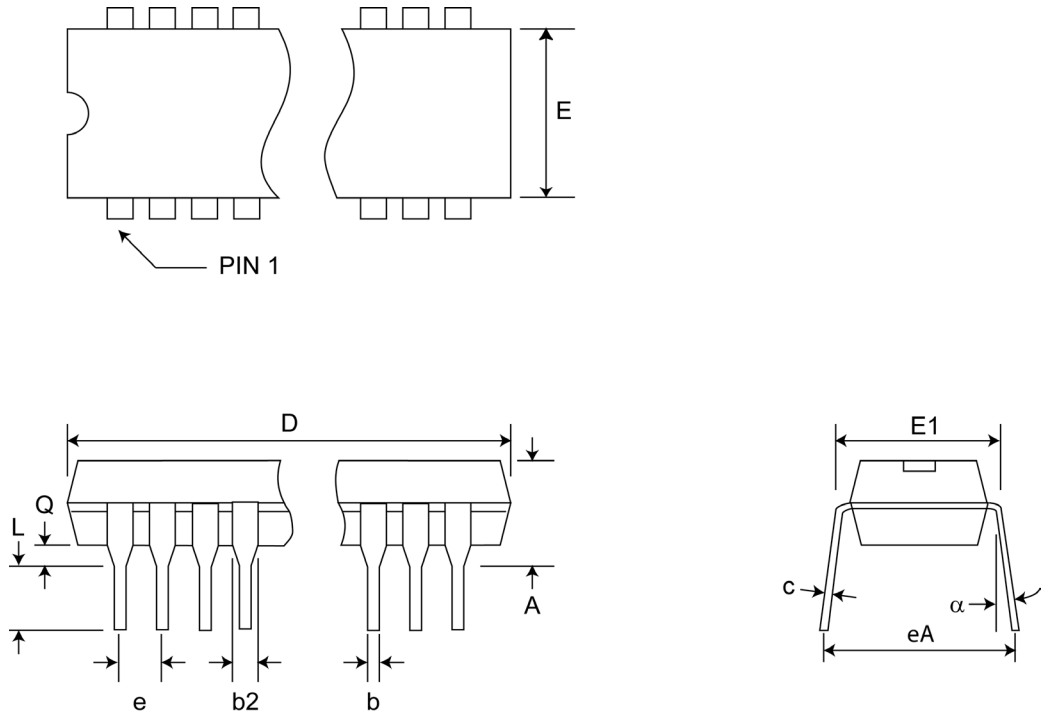
Pkg #	<b>P5</b>	
# Pins	28 (300 mil)	
Symbol	<b>Min</b>	<b>Max</b>
A	-	0.210
A1	-	
b	0.014	0.023
b2	0.045	0.070
C	0.008	0.014
D	1.345	1.400
E1	0.270	0.300
E	0.300	0.380
e	0.100 BSC	
eB	-	0.430
L	0.115	0.150
$\alpha$	0°	15°





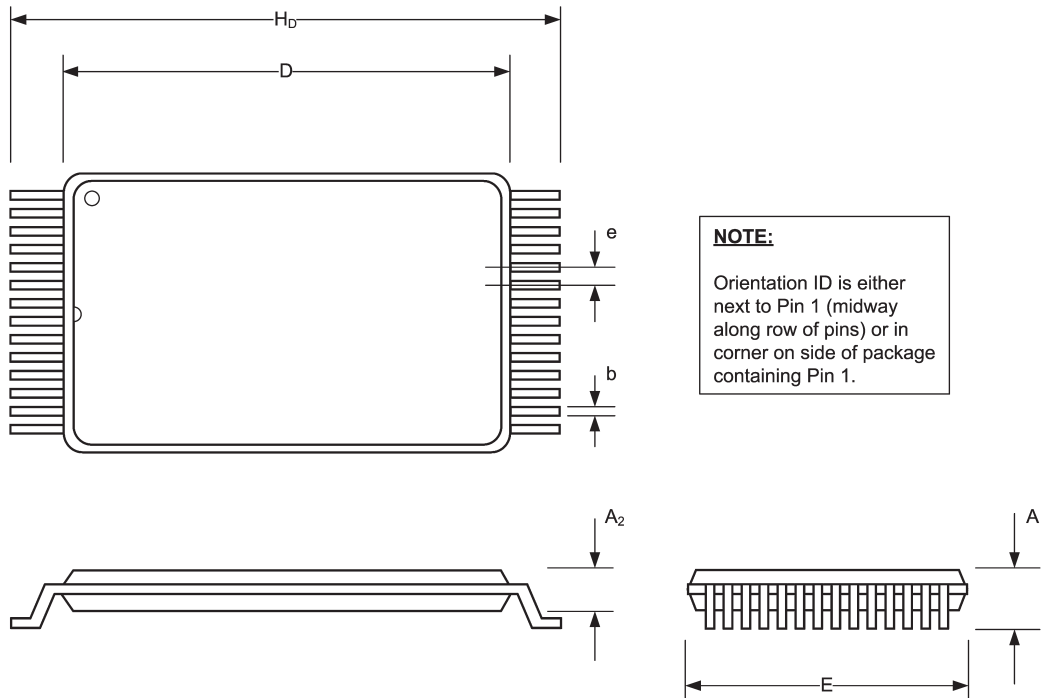
Pkg #	P6	
# Pins	28 (600 mil)	
Symbol	Min	Max
A	0.090	0.200
A1	0.000	0.070
b	0.014	0.020
b2	0.015	0.065
C	0.008	0.012
D	1.380	1.480
E1	0.485	0.550
E	0.600	0.625
e	0.100 BSC	
eB	0.600 TYP	
L	0.100	0.200
$\alpha$	0°	15°

**PLASTIC DUAL IN-LINE PACKAGE**



Pkg #	T1	
# Pins	28	
Symbol	Min	Max
A	0.039	0.047
A <sub>2</sub>	0.036	0.040
b	0.007	0.011
D	0.461	0.469
E	0.311	0.319
e	0.022 BSC	
H <sub>D</sub>	0.520	0.535

**TSOP THIN SMALL OUTLINE PACKACGE (8 x 13.4 mm)**

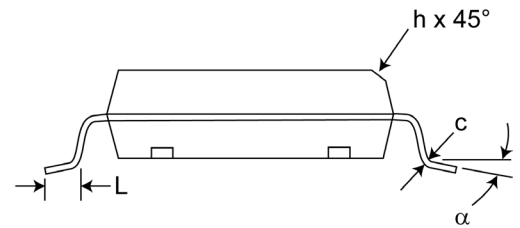
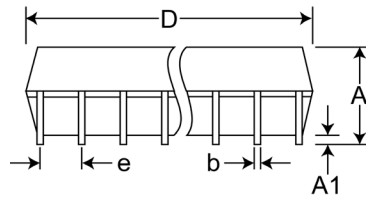
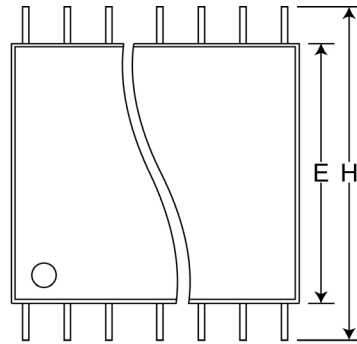


**NOTE:**  
Orientation ID is either next to Pin 1 (midway along row of pins) or in corner on side of package containing Pin 1.



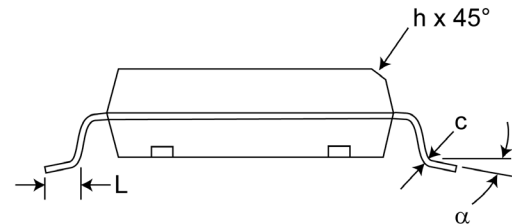
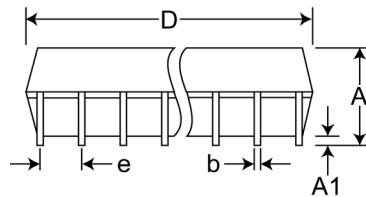
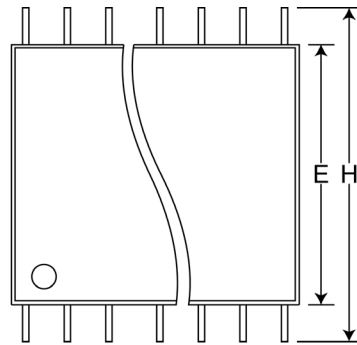
**SOIC/SOP SMALL OUTLINE IC PACKAGE**

Pkg #	<b>S11-1</b>	
# Pins	28 (300 Mil)	
Symbol	Min	Max
A	0.093	0.104
A1	0.004	0.012
b2	0.013	0.020
C	0.009	0.012
D	0.696	0.712
e	0.050 BSC	
E	0.291	0.299
H	0.394	0.419
h	0.010	0.029
L	0.016	0.050
$\alpha$	0°	8°



Pkg #	<b>S11-3</b>	
# Pins	28 (300 Mil)	
Symbol	Min	Max
A	0.094	0.110
A1	0.002	0.014
B	0.014	0.020
C	0.008	0.012
D	0.702	0.710
e	0.050 BSC	
E	0.291	0.300
H	0.463	0.477
h	0.010	0.029
L	0.020	0.042
	0°	8°

**SOIC/SOP SMALL OUTLINE IC PACKAGE**



**REVISIONS**

<b>DOCUMENT NUMBER</b>	SRAM 119
<b>DOCUMENT TITLE</b>	P4C1256 HIGH SPEED 32K x 8 STATIC CMOS RAM

<b>REV</b>	<b>ISSUE DATE</b>	<b>ORIGINATOR</b>	<b>DESCRIPTION OF CHANGE</b>
OR	1997	RKK	New Data Sheet
A	Oct-2005	JDB	Changed logo to Pyramid
B	Oct-2005	JDB	Added SOP package
C	Apr-2006	JDB	Added Lead-Free to ordering information
D	May-2006	JDB	Added PDIP to ordering information
E	Jun-2006	JDB	Added ceramic DIP package
F	Aug-2006	JDB	Updated SOJ package information
G	Jun-2007	JDB	Corrected SOP package information
H	July-2009	JDB	Added 28-pin 600 mil CERDIP, 600 mil PDIP.
I	July 2010	JDB	Added 28-pin Solder Seal Flat Pack